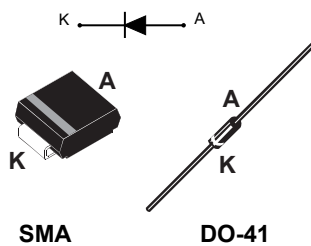




# THE DATASHEET OF STPS1150A



## 150 V power Schottky rectifier



### Features

- Negligible switching losses
- Low forward voltage drop for higher efficiency and extended battery life
- Low thermal resistance
- Surface mount miniature package
- Avalanche capability
- ECOPACK<sup>®</sup>2 compliant component

### Applications

- Switching diode
- SMPS
- DC/DC converter
- Telecom power

### Description

This 150 V power Schottky rectifier is ideal for switch mode power supplies on up to 24 V rails and high frequency converters.

Packaged in SMA and axial, the **STPS1150** is optimized for use in consumer and computer applications where low drop forward voltage is required to reduce power dissipation.

Product status	
STPS1150	
Product summary	
Symbol	Values
$I_{F(AV)}$	1 A
$V_{RRM}$	150 V
$T_j(max.)$	175 °C
$V_{F(typ.)}$	0.62 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values, at 25 °C, unless otherwise specified)**

Symbol	Parameter		Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage		150	V	
$I_{F(RMS)}$	Forward rms current		15	A	
$I_{F(AV)}$	Average forward current $\delta = 0.5$ , square wave	SMA	$T_L = 150\text{ °C}$	1	A
		DO-41	$T_L = 150\text{ °C}$		
$I_{FSM}$	Surge non repetitive forward current	SMA	$t_p = 10\text{ ms sinusoidal}$	50	A
		DO-41		75	
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 10\text{ }\mu\text{s}, T_j = 125\text{ °C}$		108	W
$T_{stg}$	Storage temperature range		-65 to + 175	°C	
$T_j$	Maximum operating junction temperature <sup>(1)</sup>		+ 175	°C	

1.  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameter**

Symbol	Parameter		Max. value	Unit	
$R_{th(j-l)}$	Junction to lead		SMA	30	°C/W
	Junction to lead	Lead length = 10 mm	DO-41	30	

For more information, please refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	0.2	1.0	$\mu\text{A}$
		$T_j = 125\text{ °C}$		-	0.2	1.0	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$	-	0.78	0.82	V
		$T_j = 125\text{ °C}$		-	0.62	0.67	
		$T_j = 25\text{ °C}$	$I_F = 2\text{ A}$	-	0.85	0.89	
		$T_j = 125\text{ °C}$		-	0.69	0.75	

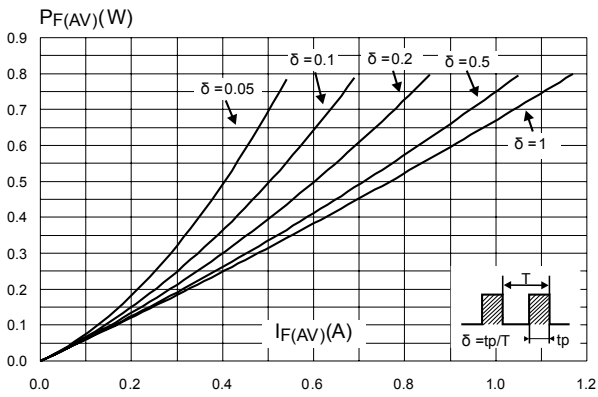
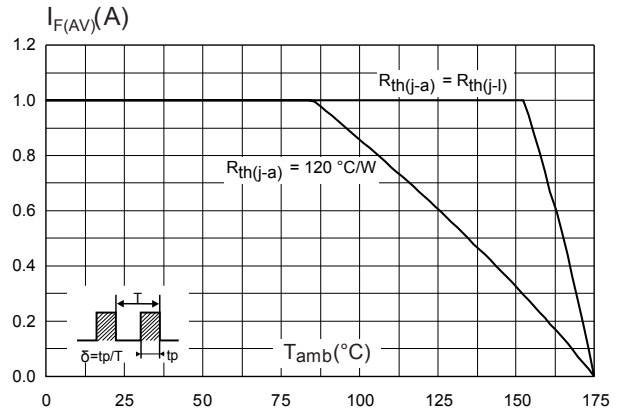
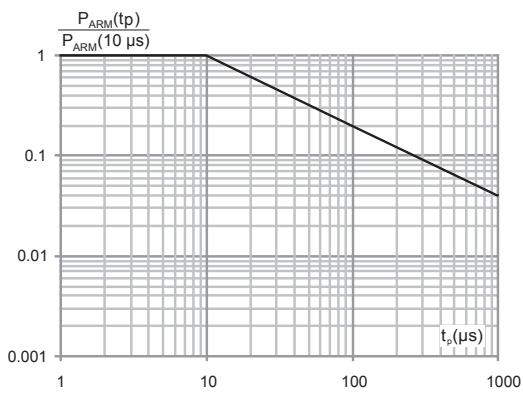
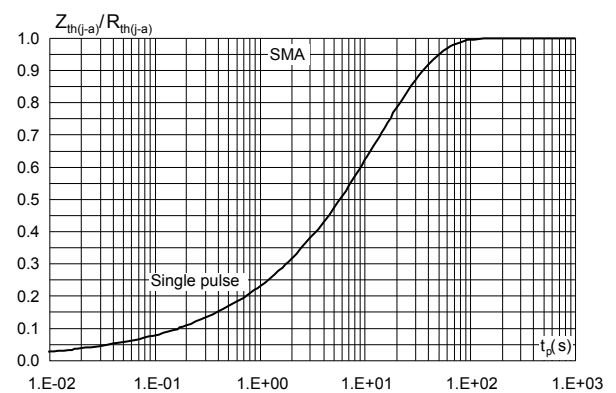
1. Pulse test:  $t_p = 5\text{ ms}, \delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}, \delta < 2\%$

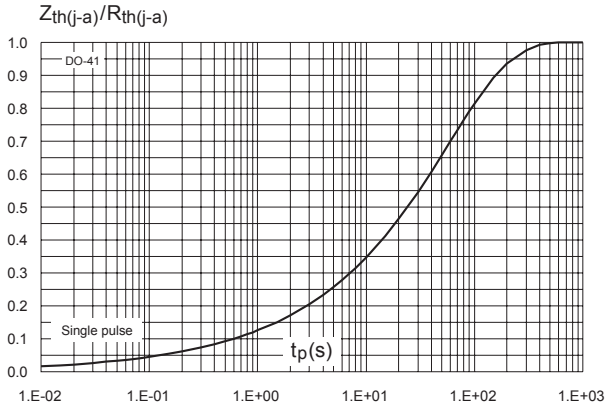
To evaluate the conduction losses use the following equation:  $P = 0.59 \times I_{F(AV)} + 0.08 I_{F(RMS)}^2$

For more information, please refer to the following application notes related to the power losses :

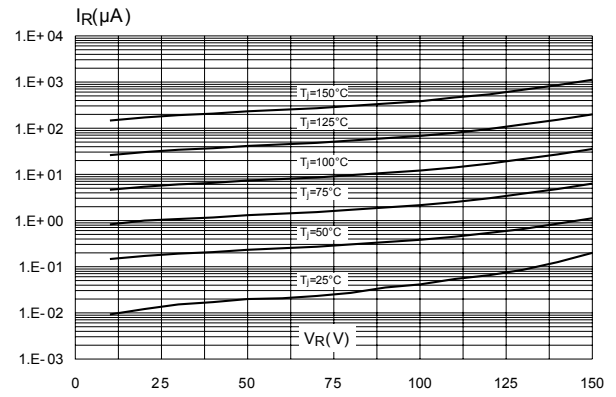
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

**1.1 Characteristics (curves)**
**Figure 1. Average forward power dissipation versus average forward current**

**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )**

**Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125^{\circ}C$ )**

**Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)**


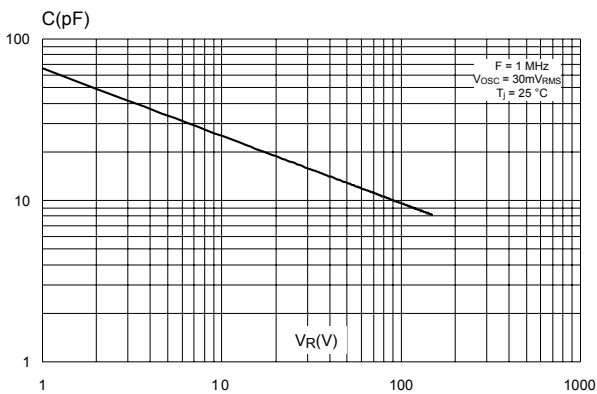
**Figure 5. Relative variation of thermal impedance junction to ambient versus pulse duration (DO-41)**



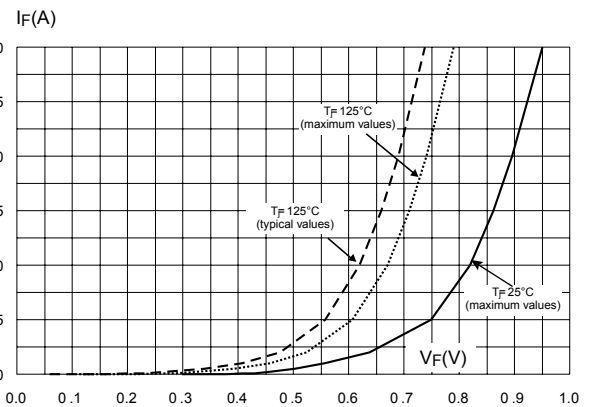
**Figure 6. Reverse leakage current versus reverse voltage applied (typical values)**



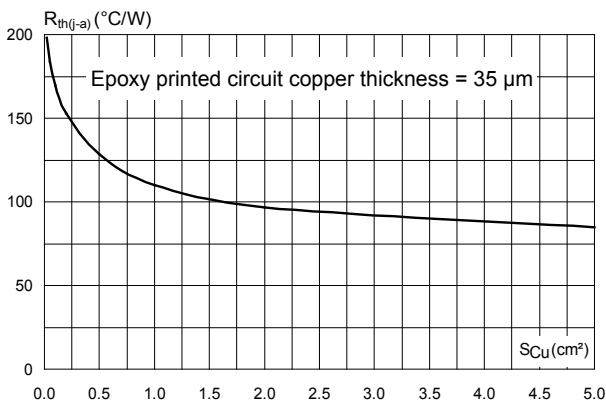
**Figure 7. Junction capacitance versus reverse voltage applied (typical values)**



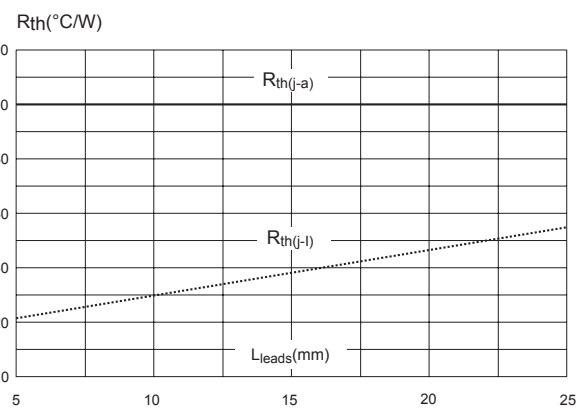
**Figure 8. Forward voltage drop versus forward current**



**Figure 9. Thermal resistance junction to ambient versus copper surface under each lead (SMA)**



**Figure 10. Thermal resistance versus lead length (DO-41)**



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 SMA package information

- Epoxy meets UL 94, V0
- Cooling method : by conduction (C)

Figure 11. SMA package outline

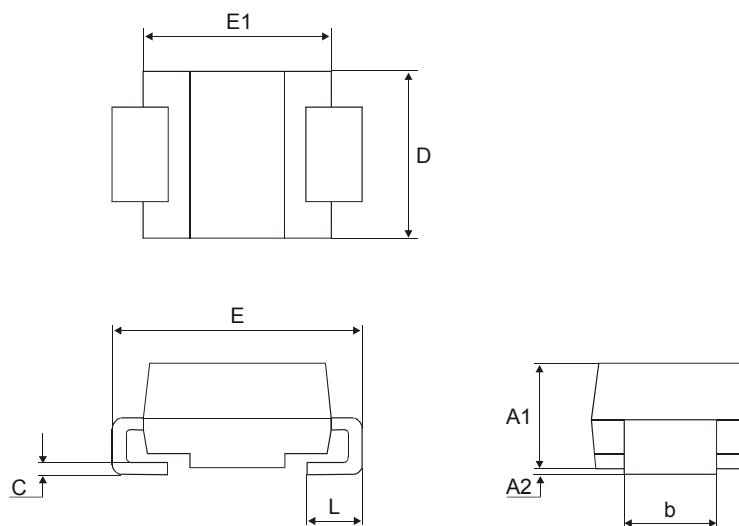
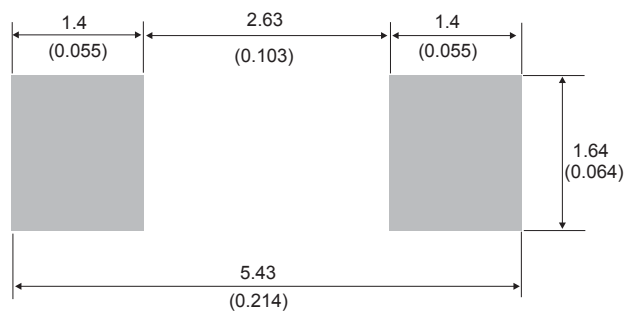


Table 4. SMA package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	1.90	-	2.45	0.075	-	0.097
A2	0.05	-	0.20	0.002	-	0.008
b	1.25	-	1.65	0.049	-	0.065
C	0.15	-	0.40	0.006	-	0.016
D	2.25	-	2.90	0.089	-	0.114
E	4.80	-	5.35	0.189	-	0.211

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
E1	3.95	-	4.60	0.156	-	0.181
L	0.75	-	1.50	0.030	-	0.059

Figure 12. SMA recommended footprint in mm (inches)



## 2.2 DO-41 package information

- Epoxy meets UL 94, V0

Figure 13. DO-41 package outline

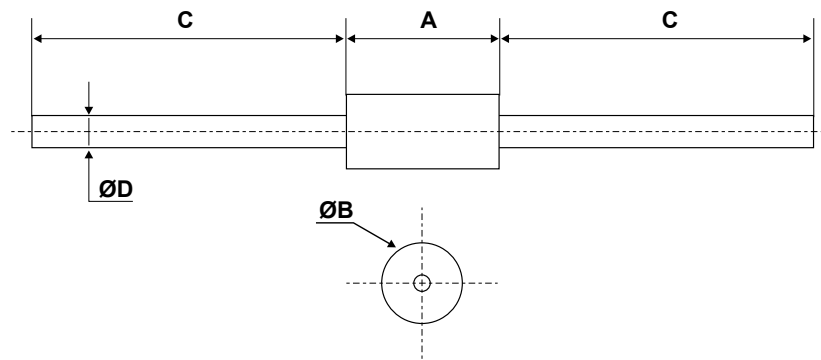


Table 5. DO-41 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.1	-	5.20	0.160	-	0.205
B	2.00	-	2.71	0.080	-	0.107
C	25.40	-		1.000	-	
D	0.71	-	0.86	0.028	-	0.0034

### 3 Ordering Information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS1150A	1150	SMA	0.068 g	5000	Tape and reel
STPS1150	STPS1150	DO-41	0.34 g	2000	Ammopack
STPS1150RL	STPS1150	DO-41	0.34 g	5000	Tape and reel

## Revision history

**Table 7. Document revision history**

Date	Version	Changes
Jul-2003	2A	Last update.
Aug-2004	3	SMA package dimensions update. Reference A1 max. changed from 2.70 mm (0.106) to 2.03 mm (0.080).
31-May-2006	4	Reformatted to current standard. Added ECOPACK statement. Updated SMA footprint in Figure 15. Changed nF to pF in Figure 10.
09-Feb-2011	5	Added STmite and STmite flat package.
15-Apr-2014	6	Updated : Features, Table 2, 3 and Figure 2. Updated Section 2: Package information.
28-Sep-2018	7	Removed STmite and STmite flat package information. Updated Table 1. Absolute ratings (limiting values, at 25 °C, unless otherwise specified) and Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125\text{ °C}$ ).

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